General Purpose NPN Epitaxial Planar Transistor

BTD1616AM3

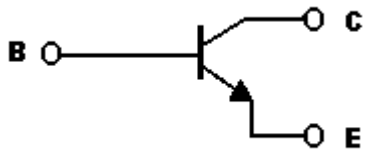
BV_{CEO}	60V
I_C	3A
$V_{CESAT(max)}$	150mV

Features

- High breakdown voltage, $BV_{CEO} \geq$ 60V
- Large continuous collector current capability
- Low collector saturation voltage
- Pb-free lead plating and halogen-free package

Symbol

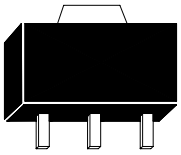
BTD1616AM3



B：Base
C：Collector
E：Emitter

Outline

SOT-89



B C E

Ordering Information

Device	Package	Shipping
BTD1616AM3-0-T2-G	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / Tape & Reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T2 :1000 pcs/tape & reel, 7” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	120	V
Collector-Emitter Voltage	V_{CEO}	60	V
Emitter-Base Voltage	V_{EBO}	7	V
Collector Current (DC)	I_C	3	A
Collector Current (pulse)	I_{CP}	5	A
Base Current	I_B	0.3	A
Power Dissipation	Pd	0.6	W
		1.5 (Note 1)	W
		2.1 (Note 2)	W
Operating Junction and Storage Temperature Range	Tj ; Tstg	-55~+150	°C

Note : 1. When mounted on 25mm×25mm×1.6 mm FR-4 PCB with high coverage of single sided 1 oz copper, in still air condition
2 . When mounted on 50mm×50mm×1.6 mm FR-4 PCB with high coverage of single sided 1 oz copper, in still air condition

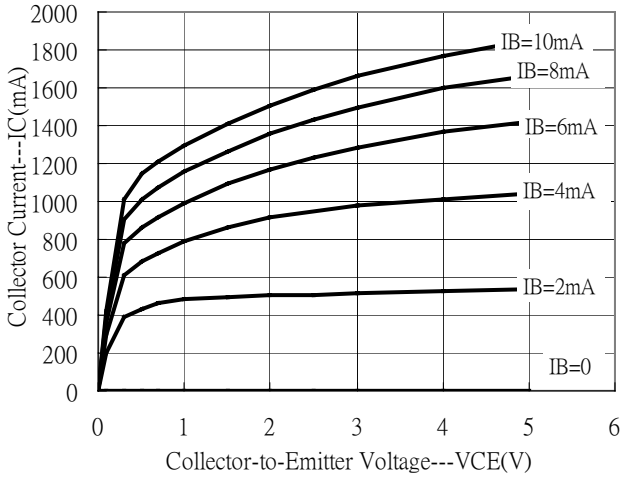
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	120	-	-	V	I_C=50μA
BV_{CEO}	60	-	-	V	I_C=1mA
BV_{EBO}	7	-	-	V	I_E=50μA
I_{CBO}	-	-	100	nA	V_{CB}=120V
I_{EBO}	-	-	100	nA	V_{EB}=7V
*$V_{CE(sat)}$	-	98	150	mV	I_C=1A, I_B=50mA
*$V_{CE(sat)}$	-	131	200	mV	I_C=1A, I_B=20mA
*$V_{BE(sat)}$	-	-	1	V	I_C=1A, I_B=50mA
*$V_{BE(on)}$	600	-	700	mV	V_{CE}=2V, I_C=50mA
*h_{FE} 1	200	-	400	-	V_{CE}=2V, I_C=100mA
*h_{FE} 2	120	-	-	-	V_{CE}=2V, I_C=1A
f_T	100	-	-	MHz	V_{CE}=2V, I_C=100mA, f=100MHz
Cob	-	11	18	pF	V_{CB}=10V, I_E=0A,f=1MHz
ton	-	40	-	ns	V_{CC}=30V, I_C=1A, I_B1=-I_B2=33mA, RL=30Ω
tstg	-	500	-		
tf	-	120	-		

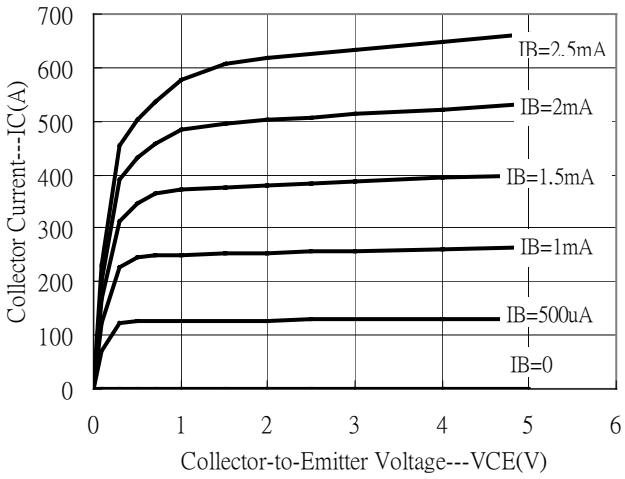
*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Typical Characteristics

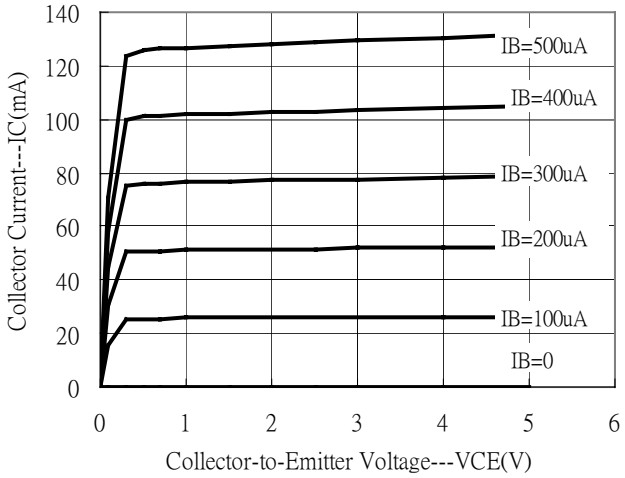
Emitter Grounded Output Characteristics



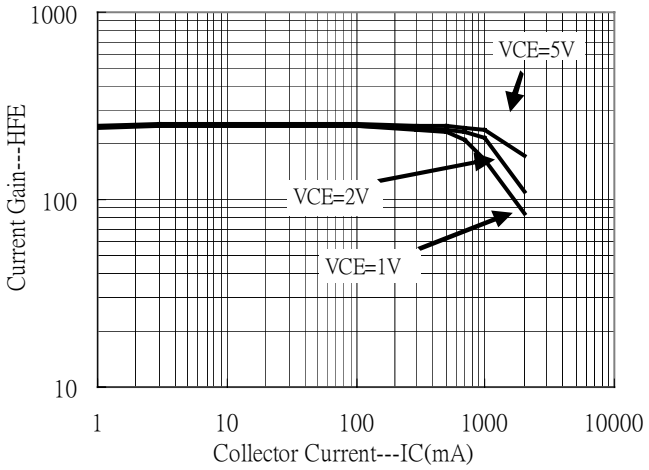
Emitter Grounded Output Characteristics



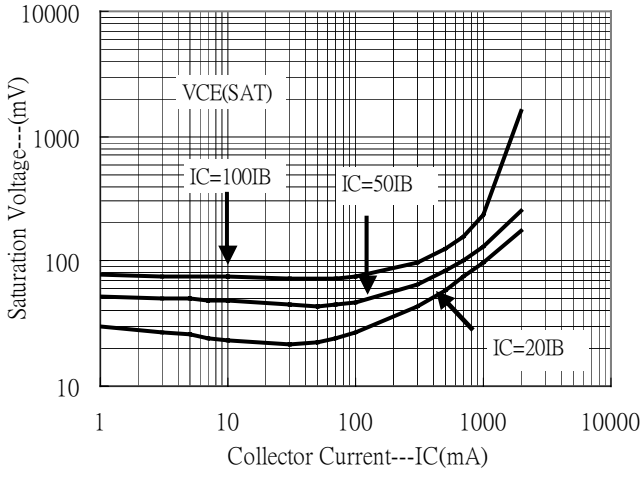
Emitter Grounded Output Characteristics



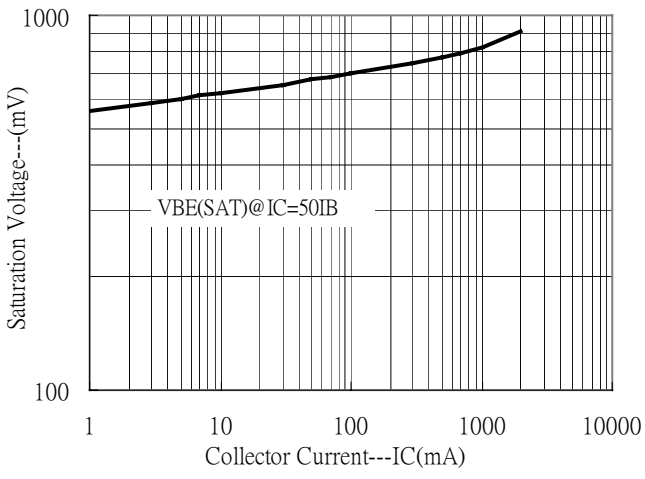
Current Gain vs Collector Current



Saturation Voltage vs Collector Current

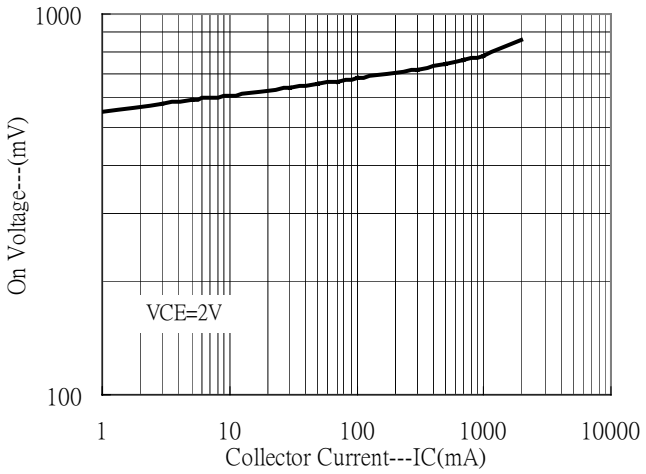


Saturation Voltage vs Collector Current

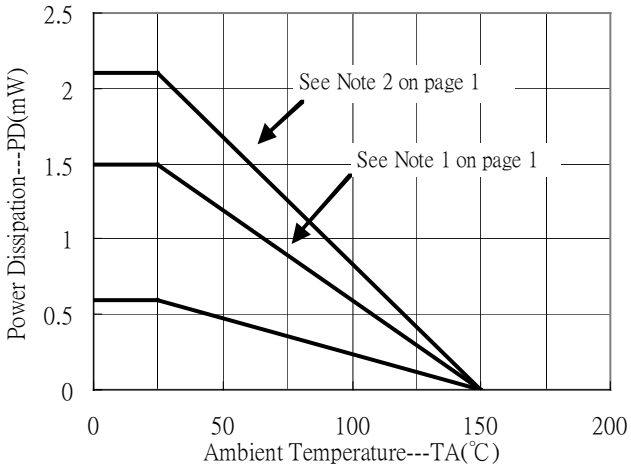


Typical Characteristic Curves(Cont.)

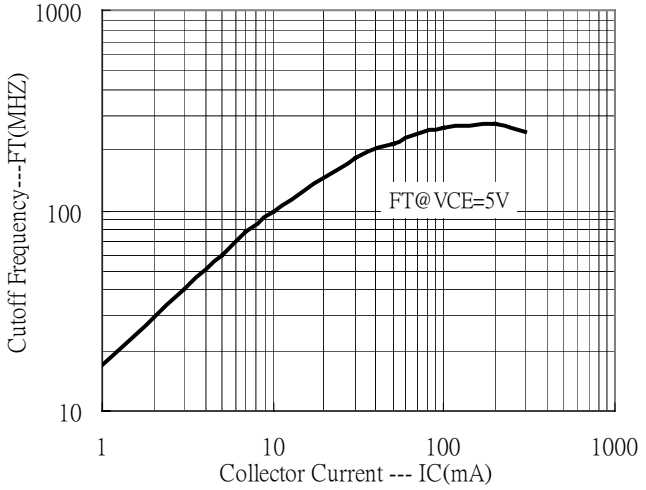
On Voltage vs Collector Current



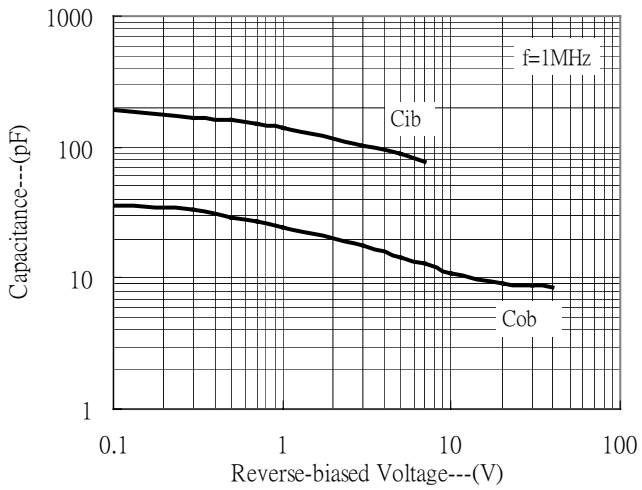
Power Derating Curves



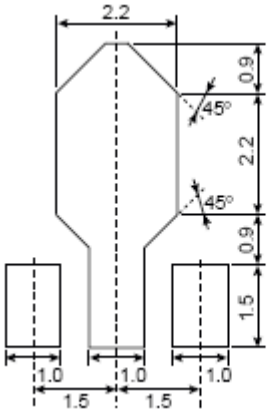
Cutoff Frequency vs Collector Current



Capacitance Characteristics

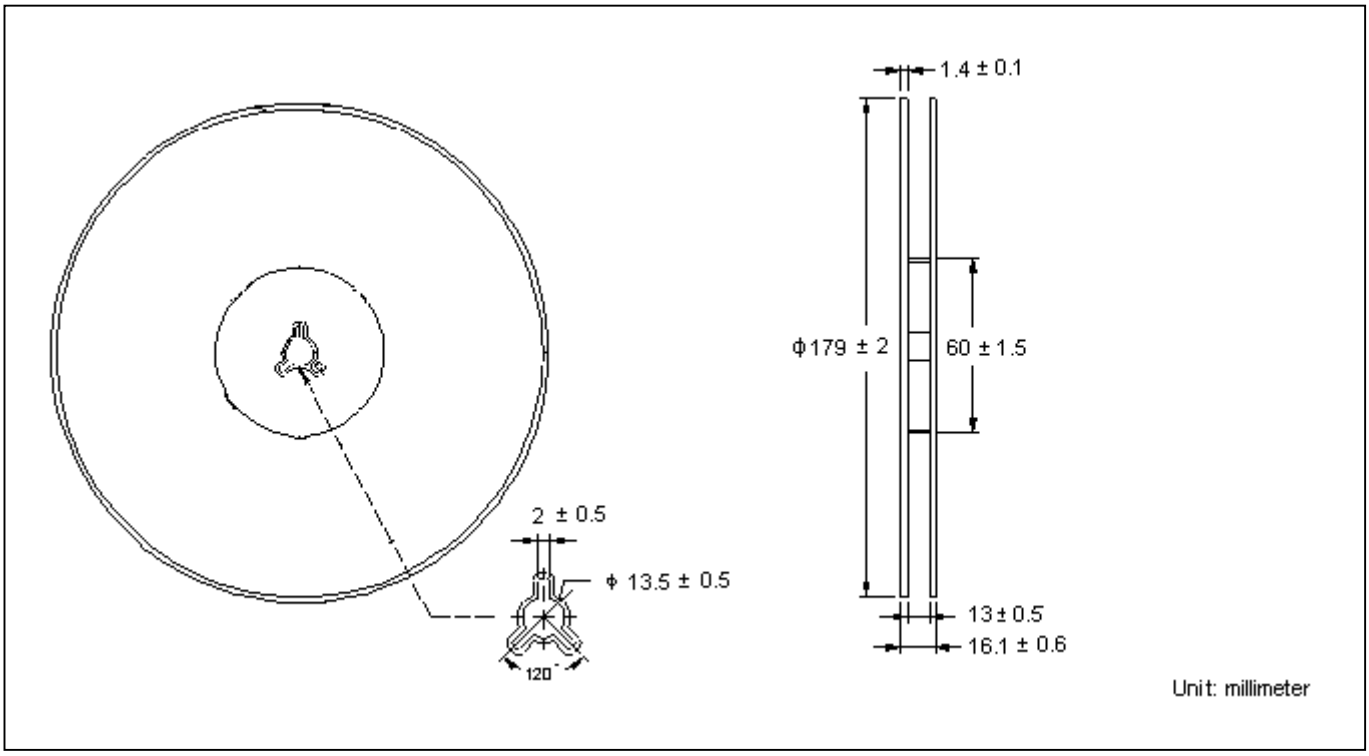


Recommended soldering footprint

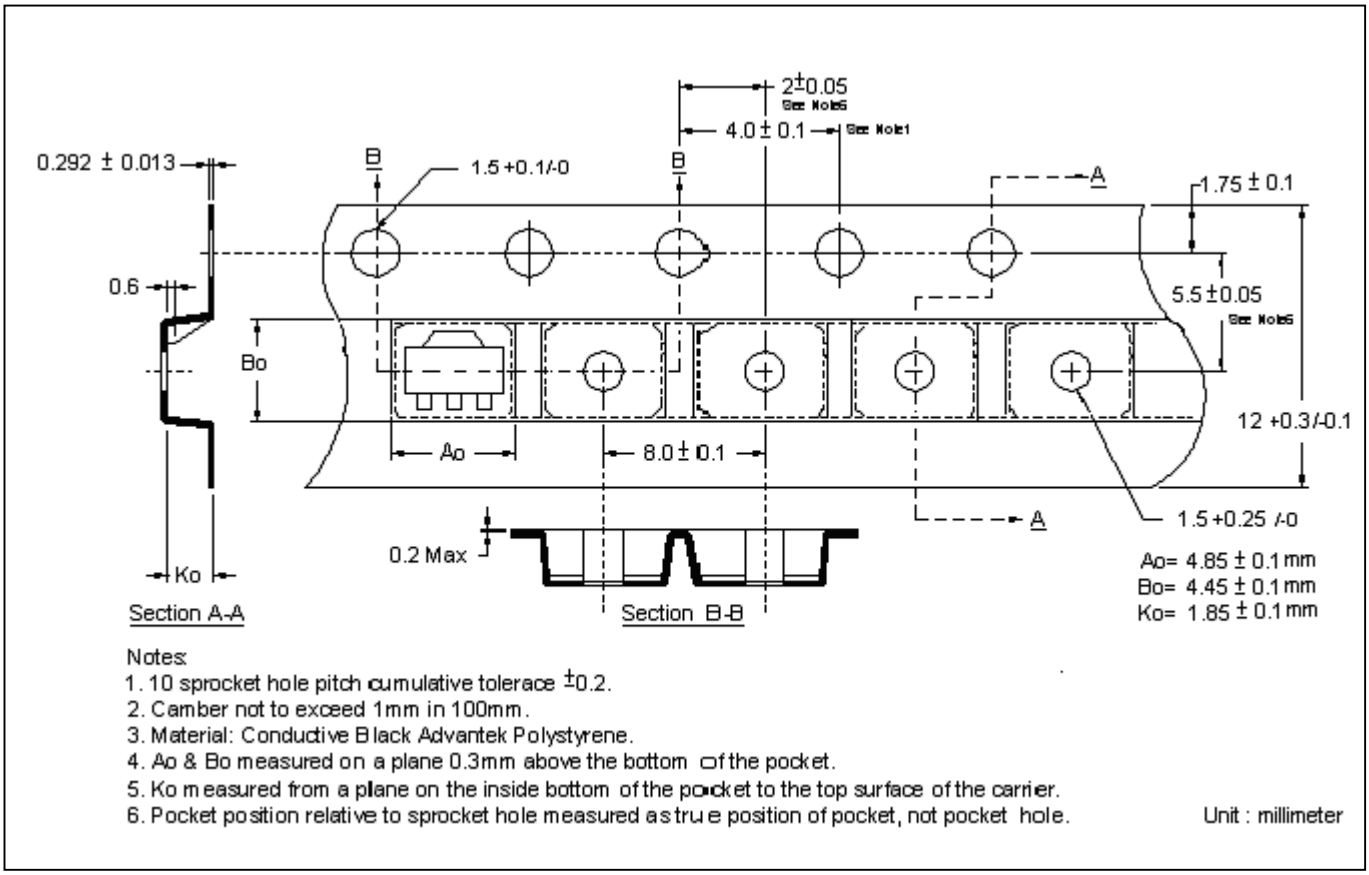


unit : mm

Reel Dimension



Carrier Tape Dimension



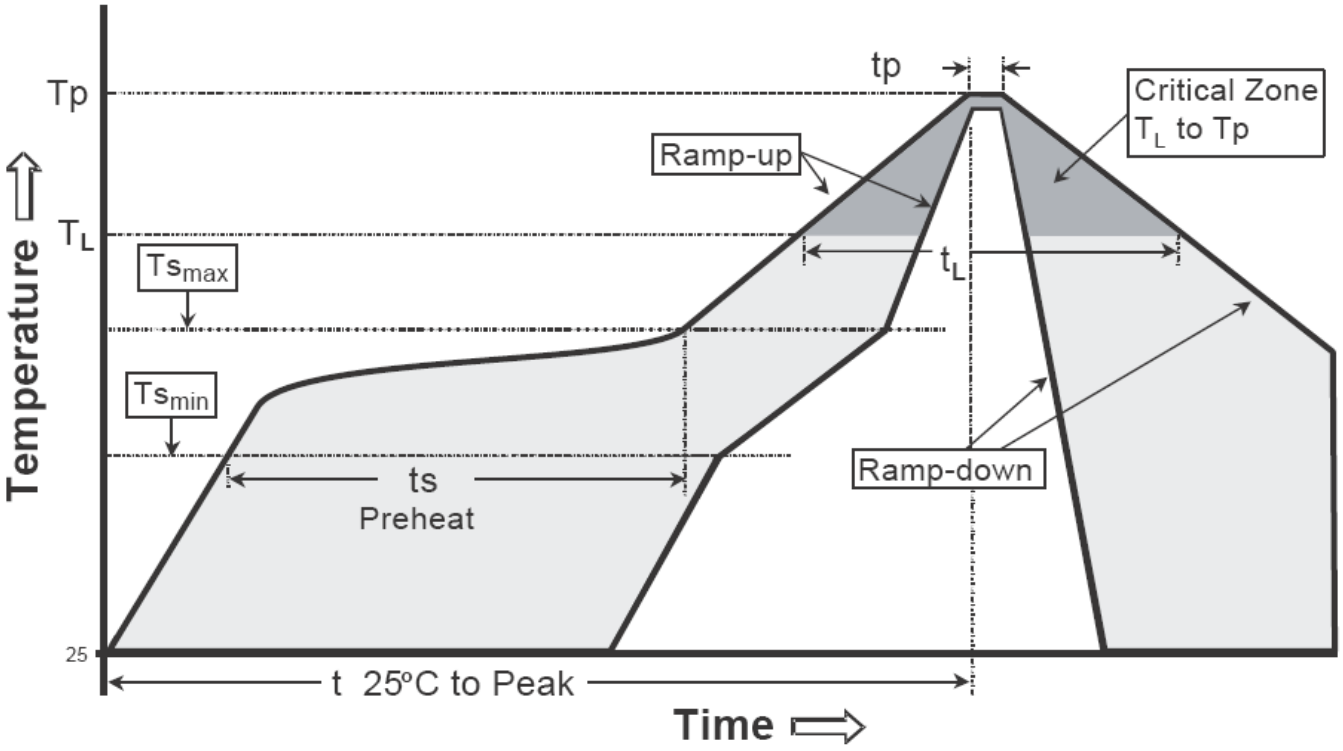
Notes:
1. 10 sprocket hole pitch cumulative tolerace ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Advantek Polystyrene.
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

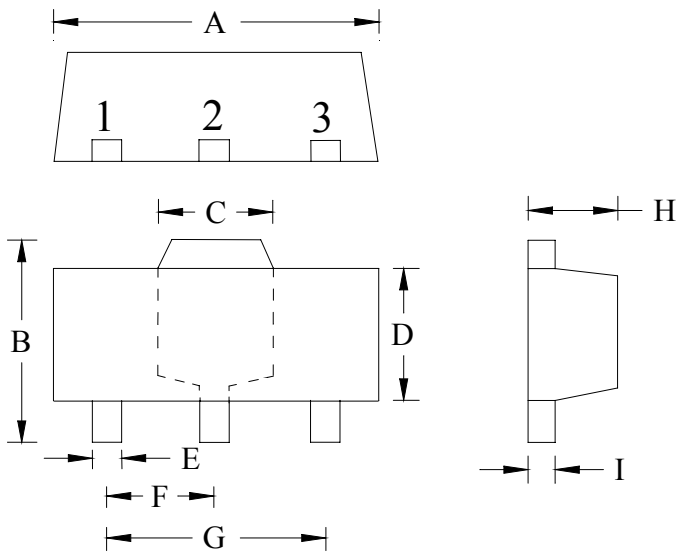
Recommended temperature profile for IR reflow

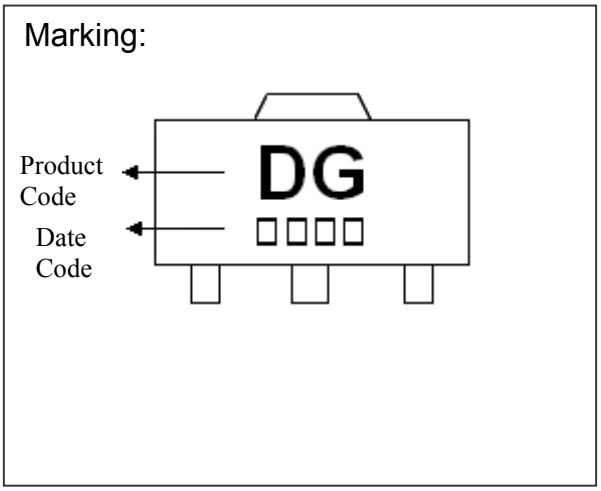


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(Ts min) −Temperature Max(Ts max) −Time(ts min to ts max)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (TL) − Time (tL)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension





Style: Pin 1. Base 2. Collector 3. Emitter

3-Lead SOT-89 Plastic
Surface Mounted Package
CYStek Package Code: M3

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591 TYP		1.50 TYP	
B	0.1551	0.1673	3.94	4.25	G	0.1181 TYP		3.00 TYP	
C	0.0610 REF		1.55 REF		H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.